



Tracker R&D

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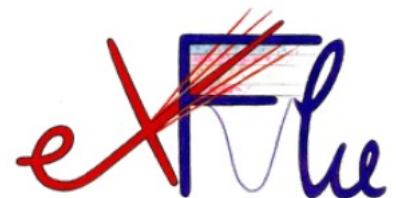
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PRIN: A compensated Design of Thin Silicon Sensors For Extreme Fluences - **ComonSens**

PRIN: DC – RSD Developments - **4D-Share 2022KLK4LB**

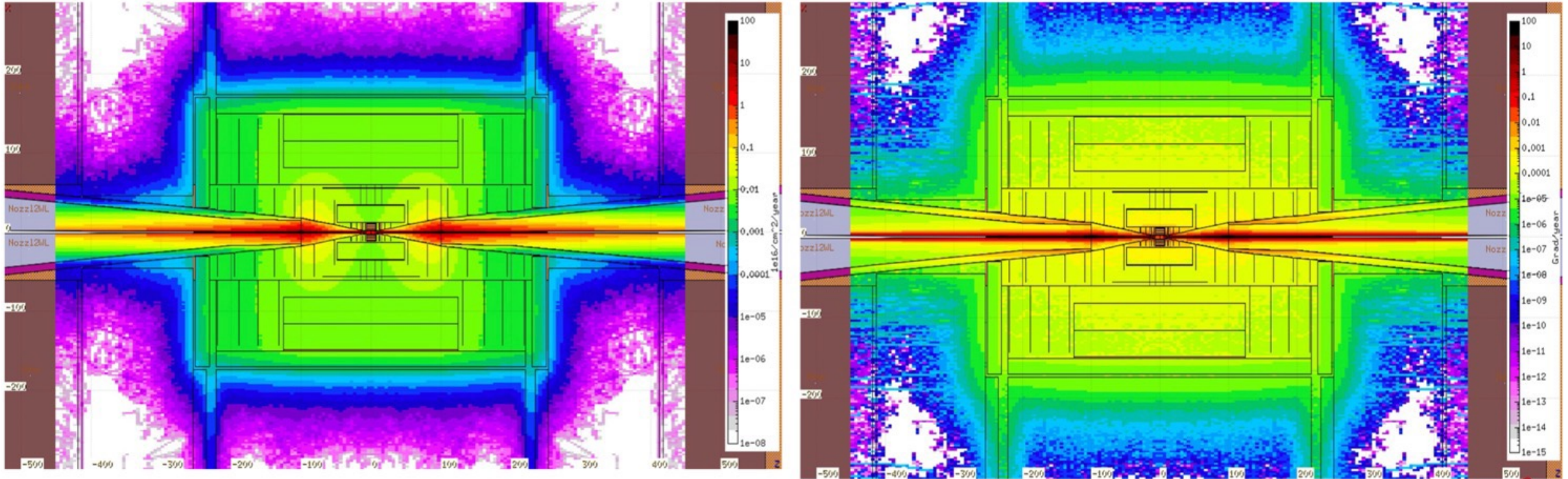


CSN5-4DSHARE



Radiation levels @1.5 TeV

1-MeV-neq fluence: one year (200 days) of operation Total Ionizing Dose: one year (200 days) of operation

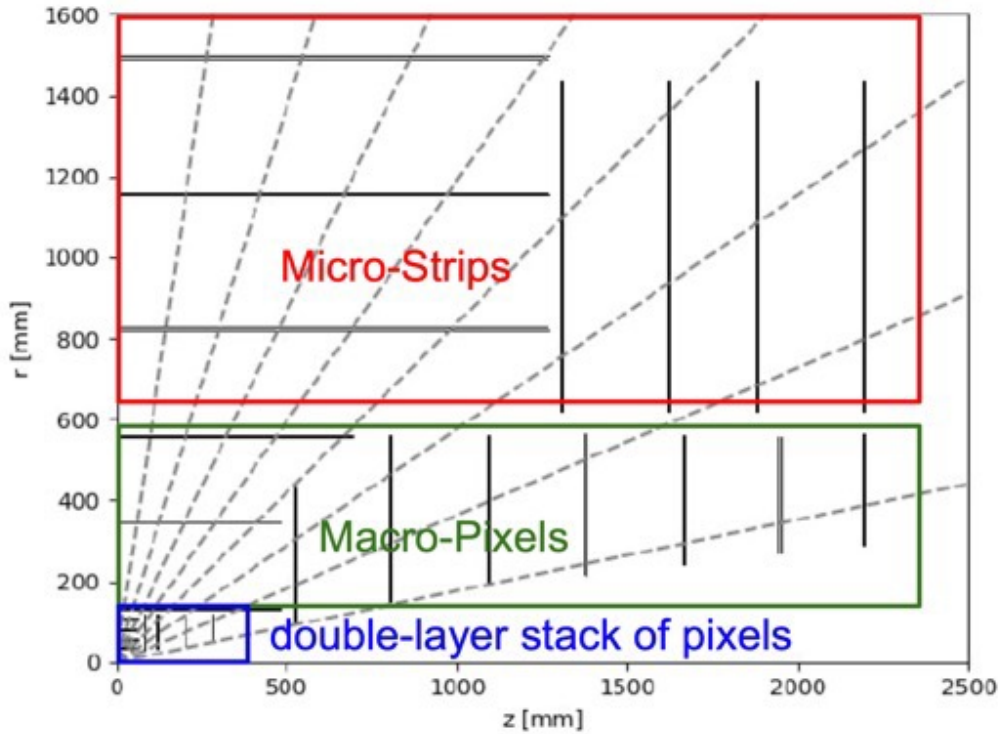


	Maximum Dose (Mrad)		Maximum Fluence (1 MeV-neq/cm ²)	
	R= 22 mm	R= 1500 mm	R= 22 mm	R= 1500 mm
Muon Collider	10	0.1	10 ¹⁵	10 ¹⁴
HL-LHC	100	0.1	10 ¹⁵	10 ¹³

Radiation hardness requirements are pretty similar to what expected at HL-LHC

Tracker layout and sensors requirements

Baseline tracking geometry

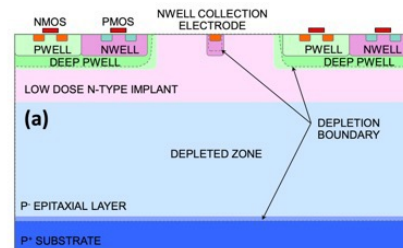


- Higher occupancies than LHC detectors are expected, but 100 kHz crossing rate (MuC with single bunch) vs 40 MHz (LHC)
- Occupancy up to 5k hit/cm² in time window of 15ns

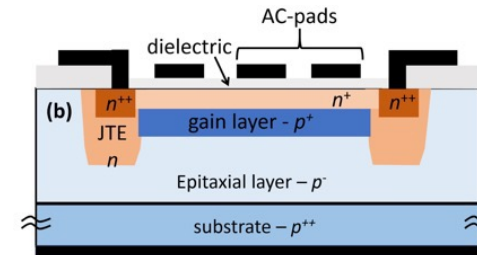
Sensors requirements

	Vertex Detector	Inner Tracker	Outer Tracker
Cell type	pixels	macropixels	microstrips
Cell Size	25 $\mu\text{m} \times 25 \mu\text{m}$	50 $\mu\text{m} \times 1 \text{mm}$	50 $\mu\text{m} \times 10 \text{mm}$
Sensor Thickness	50 μm	100 μm	100 μm
Time Resolution	30 ps	60 ps	60 ps
Spatial Resolution	5 $\mu\text{m} \times 5 \mu\text{m}$	7 $\mu\text{m} \times 90 \mu\text{m}$	7 $\mu\text{m} \times 90 \mu\text{m}$

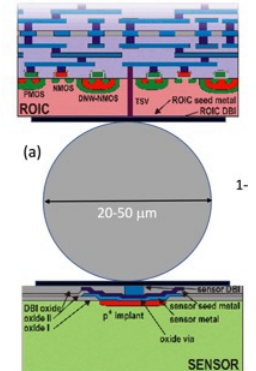
Sinergy with timing sensors development for HL-LHC



Monolithic devices (CMOS):
Good timing and spacial resolution, radiation hardness to be improved



Low Gain Avalanche Detectors (LGAD):
Large and fast signal (20-30 ps resolution), moderate radiation hardness



Hybrid small pixel devices:
Fast timing (20-30 ps resolution) and good position resolution. Intrinsically radiation hard

LGAD sensors towards 4D tracking

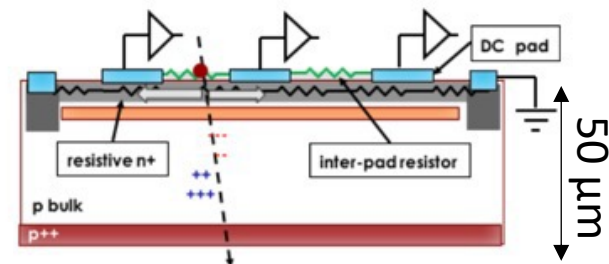
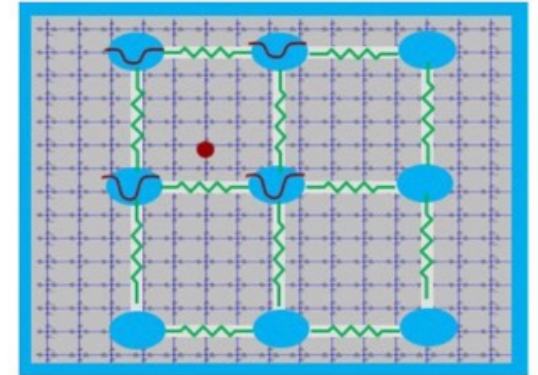
AC-RSD → and DC-RSD

DC-coupled resistive readout in silicon sensors with internal gain: signal sharing for future 4D tracking

- Project goal: evolve the resistive AC-LGAD design, improving the performance and scalability to large devices
→ realization of DC-RSD sensors (DC-coupled Resistive Silicon Detectors)
- Key points: achieve controlled signal sharing in a predetermined number of pads and drain the device leakage current at every pixel

Current status and outlook of the project for 2024:

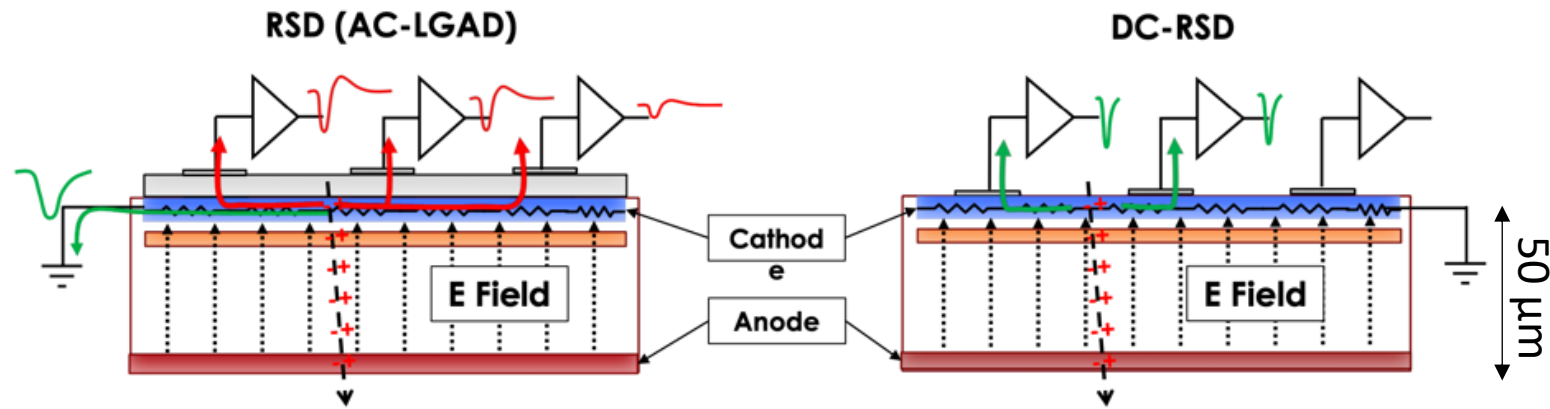
1. Completed first round of simulations for the device, using analytic modeling, SPICE and TCAD
2. Working on the process flow to manufacture DC-RSD: currently completing a few *short-loops* to acquire the necessary technical skills needed for DC-RSD
3. The first prototype run of DC-RSD should be submitted for the end of the year
4. The production should be ready for extensive testing in Q2/24 (with subsequent irradiation)



PRIN: DC – RSD Developments - 4D-Share 2022KLK4LB

LGAD sensors towards 4D tracking

From AC-RSD to DC-RSD



The design has been manufactured in several production by FBK, BNL and HPK

This design is presently under development by FBK
The main advantages of the DC-RSD design are:

- The ability to control the signal spread and
- Monopolar signal with temporal duration of few ns, rather than bipolar with long tail

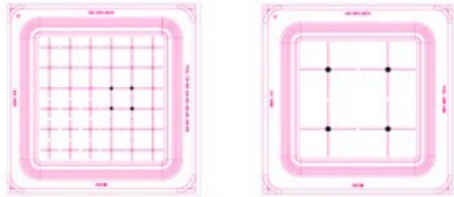
Both features are fundamental to reduce the sensor occupancy

LGAD sensors towards 4D tracking -- AC- and DC-RSD

Extensive characterization of AC-RSD in laboratory

Beam test campaign on-going

Study of RSD2: summary of past results (TCT)

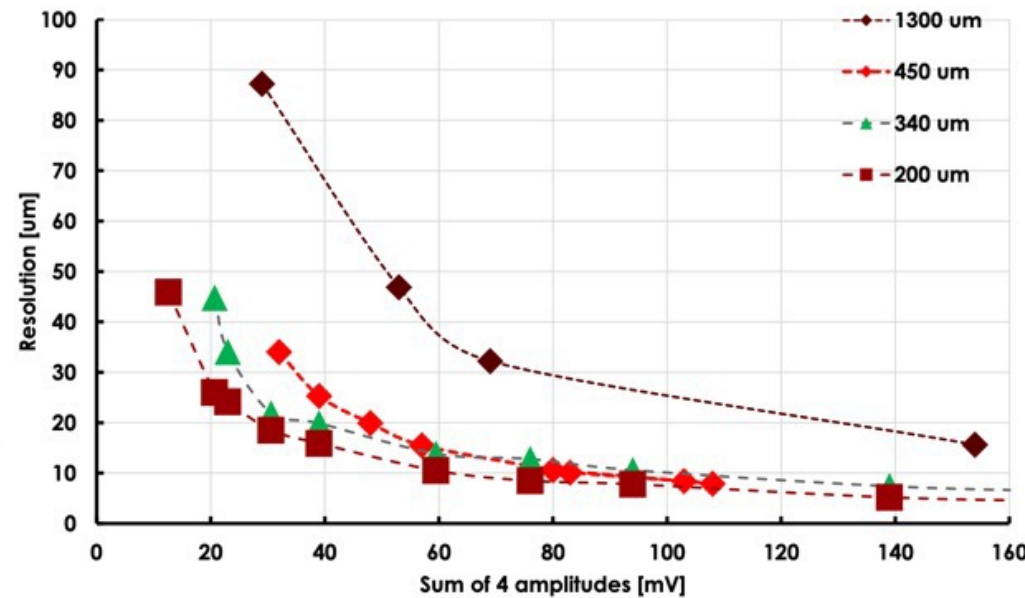


$$x_i = x_{center} + k_x \frac{pitch}{2} * \frac{Q_3 + Q_4 - (Q_1 + Q_2)}{Q_{tot}}$$

$$y_i = y_{center} + k_y \frac{pitch}{2} * \frac{Q_1 + Q_3 - (Q_2 + Q_4)}{Q_{tot}}$$

- The hit position is obtained using charge imbalance
- The resolution is defined as the difference between the laser and the reconstructed position

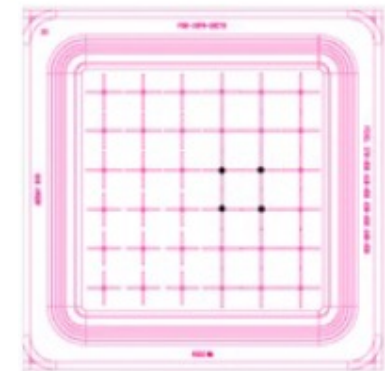
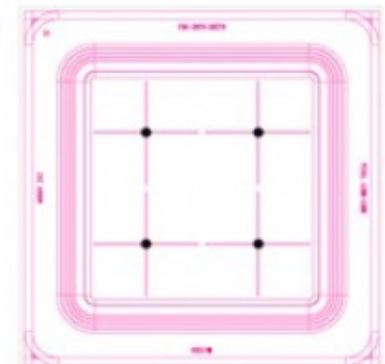
RSD2 Crosses: spatial resolution for 4 different pixel pitches



FBK-RSD2, two geometries

4 electrodes, 1300 x 1300 um²

36 electrodes, 450 x 450 um²



Spatial resolution in RSD overcomes the limit of $pitch/\sqrt{12}$ from binary readout

LGAD sensors for extreme fluences ($10^{16} - 10^{17} n_{eq}/cm^2$)

Sensori per Fluenze Estreme



Obiettivo: Realizzare sensori sottili al silicio che operino fino a fluenze di $10^{17} n_{eq}/cm^2$

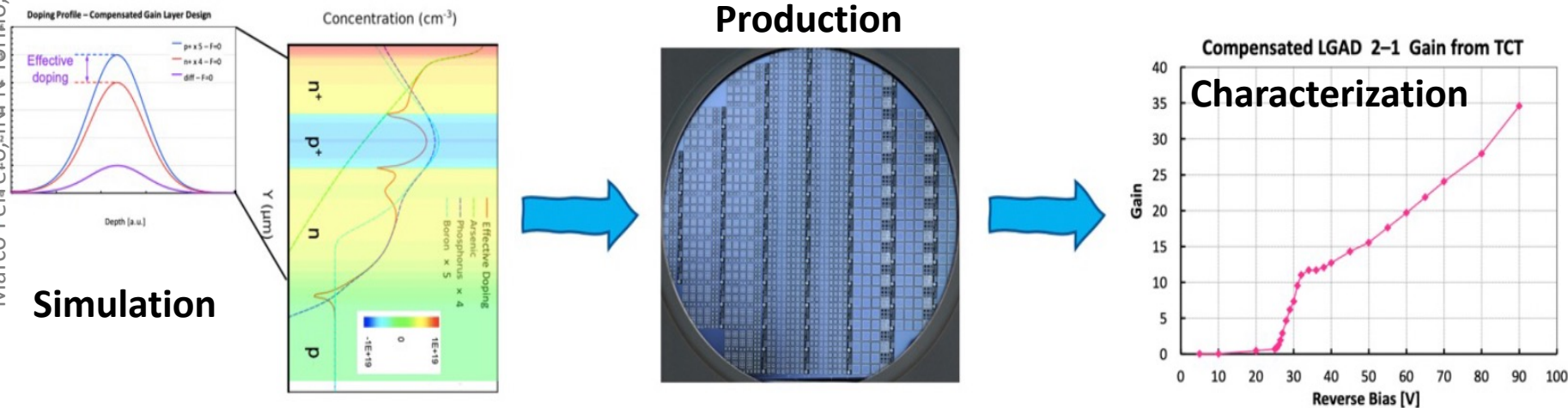
- Misurare le **proprietà dei sensori al silicio** a fluenze superiori a $10^{16} n_{eq}/cm^2$
- Disegnare e produrre **sensori planari con guadagno** in grado di operare a fluenze di $10^{16} - 10^{17} n_{eq}/cm^2$

Produzione di sensori al silicio

- La prima produzione di sensori LGAD con *gain implant* p-n compensato
→ produzione di sensori completata a fine 2022, ora in fase di caratterizzazione e irraggiamento

First prototypes of compensated-LGAD Produced by FBK in EXFLU1 production and by HPK

Extensive testing campaign on irradiated devices is on-going



DRD3 Solid State Detector Program and Working Groups



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DRD3

Nicolo Cartiglia (INFN Torino)

Two building blocks: DRDTs and WGs

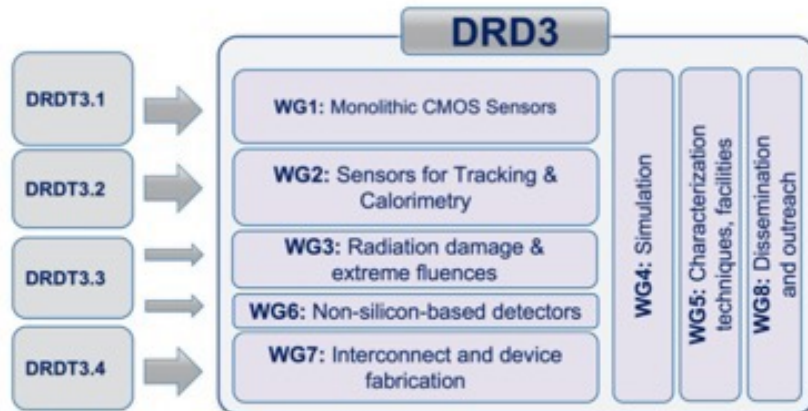
From roadmap

Social networks

DRDT 3.1 CMOS sensors	DRDT 3.2 Sensors for 4D-tracking
DRDT 3.3 Sensors for extreme fluences	DRDT 3.4 A demonstrator of 3D-integration

Table 1: The four strategic DRDTs of DRD3

- 2 • WG1 Monolithic CMOS Sensors
- 3 • WG2 Sensors for Tracking and Calorimetry
- 4 • WG3 Radiation damage and extreme fluences
- 5 • WG4 Simulation
- 5 • WG5 Characterization techniques, facilities
- 7 • WG6 Non-silicon-based sensors
- 8 • WG7 Interconnect and device fabrication
- 9 • WG8 Dissemination and outreach



DRD3 proto-collaboration
~ 100 groups – 75% from Europe

- The most considerable interplay of DRD3 is with DRD7 (electronics), on the field of the DMAPS
- There is no DRD3 group that has expressed interest in silicon for calorimetry
- The plane to collaborate with industry in the same way we did in RD50

Outlook for the future

- Development of a reliable sensor technology requires a couple of sensors production (2-3 years)

DC-RSD

- First DC-RSD production will be ready for the Q2/2024
- A second DC-RSD batch is scheduled for the 2025

SENSORS for EXTREME FLUENCES

- The characterization of the first batch of Compensated-LGAD is on-going
- A second production is scheduled for the end of 2024

It is reasonable to have target prototypes in 2026, after 3 years of R&D

- Characterization results are an important input for realistic digitization in the physics and detector simulation

Backup

Occupancy

